



PK493 (v1.1) March 19, 2011

100% Material Declaration Data Sheet for Spartan®-3/-3E CP132 (Cu Wire)

Average Weight: 0.1190 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die (FPGA)					0.015196	12.770
	Silicon (Si)	7440-21-3	100.00		0.015196	
Die Attach Adhesive					0.002706	2.274
	Silver (Ag)	7440-22-4	77.50		0.002097	
	Bismaleimide monomer	Trade secret	15.00		0.000406	
	Acrylate monomer	Trade secret	7.50		0.000203	
Copper Wire					0.000469	0.394
	Copper (Cu)	7440-50-8	97.28		0.000456	
	Palladium	7440-05-3	2.70		0.000013	
	Impurities	N/A	0.02		0.000000	
Substrate					0.031177	26.199
	Copper (Cu)	7440-50-8	36.71		0.011444	
	Nickel (Ni)	7440-02-0	1.90		0.000593	
	Gold (Au)	7440-57-5	0.21		0.000064	
	Glass fiber	65997-17-3	19.26		0.006003	
	Non-halogen fire retardant	Trade Secret	11.13		0.003469	
	BT (core)	Trade Secret	12.41		0.003869	
Solder mask	Trade Secret	18.40		0.005735		

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Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Mold Compound					0.055631	46.749
	Epoxy Resin	Trade secret	5.00		0.002782	
	Phenol Resin	Trade secret	3.00		0.001669	
	Phenol Novolac	9003-35-4	3.00		0.001669	
	Metal hydroxide	Trade secret	3.00		0.001669	
	Carbon Black	1333-86-4	0.30		0.000167	
	Fused Silica	60676-86-0	70.40		0.039164	
	Fused Silica	7631-86-9	15.00		0.008345	
Silica crystalline	14808-60-7	0.30		0.000167		
Solder Balls					0.013821	11.614
	Tin (Sn)	7440-31-5	63.00		0.008707	
	Lead (Pb)	7439-92-1	37.00		0.005114	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/16/11	1.0	Initial Xilinx release.
03/19/12	1.1	Device family update.

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